

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No. : 10/521333 Confirmation No. N/A
 Applicant : Mitsuhiro Funaki et al.
 Filed : January 18, 2005
 TC/A.U. : N/A
 Examiner : N/A
 Title : COPPER ALLOY, COPPER ALLOY PRODUCING
 METHOD, COPPER COMPLEX MATERIAL, AND
 COPPER COMPLEX MATERIAL PRODUCING
 METHOD
 Docket No. : KOY-15896
 Customer No. : 040854

LETTER

Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

Sir/Madam:

Applicant encloses herewith the required Declaration for the above-identified application. The \$130.00 fee to cover the late filing fee surcharge for the enclosed declaration was included in the filing fee sent on January 18, 2005.

If there are any further fees resulting from this communication not covered by the fee sent on January 18, 2005, please charge the same to Deposit Account No. 18-0160, Order No. KOY-15896.

Respectfully submitted,

RANKIN, HILL, PORTER & CLARK LLP

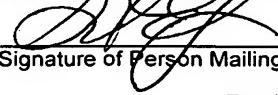
By



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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date indicated below.



Signature of Person Mailing Paper

3/11/05
Date

David E. Spaw
Printed Name of Person Mailing Paper